

ABSTRACT OF THE DISCLOSURE

A method for producing a molded flip chip package is described. The incomplete flip chip package comprising a thin substrate and a silicon chip is placed in a mold. A resin, preferably epoxy, is injected into the mold filling the gap between the surface of the flip chip and the adjacent substrate. Additionally, a stiffening structure is formed to increase the overall rigidity of the thin substrate specifically and the package as a whole.

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